

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t	E r r o r s
1	BRS	L1	20914 6	pcb (printed adj circuit)	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 13:06		0
2	BRS	L2	3233	1 with inspect\$	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 13:06		0
3	BRS	L3	7076	1 same (group\$3 cluster\$3)	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 14:02		0
4	BRS	L4	58	2 same (group\$3 cluster\$3)	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 14:01		0
5	BRS	L5	7758	wafer with inspect\$	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 14:22		0
6	BRS	L6	311	5 same (group\$3 cluster\$3)	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 14:04		0
7	BRS	L7	203	5 same (group\$3 cluster\$3)	USPAT; EPO; DERWENT	2003/09/25 14:22		0
8	BRS	L8	24440	(chip die) same (group\$3 cluster\$3)	USPAT; EPO; DERWENT	2003/09/25 14:22		0
9	BRS	L9	222	8 and (wafer with inspect\$)	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 14:23		0
10	BRS	L10	45	8 same (wafer with inspect\$)	USPAT; US-PGPUB; EPO; DERWENT	2003/09/25 14:23		0